

Title (en)

THIN PLATE METAL PUNCHING DIE AND THIN PLATE METAL PUNCHING APPARATUS PROVIDED WITH THE DIE

Title (de)

DÜNNBLECHSTANZWERKZEUG UND MIT DEM WERKZEUG VERSEHENE DÜNNBLECHSTANZVORRICHTUNG

Title (fr)

MATRICE DE PERFORATION DE MÉTAL EN PLAQUE MINCE ET APPAREIL DE PERFORATION DE MÉTAL EN PLAQUE MINCE POURVU DE LA MATRICE

Publication

**EP 2153915 A4 20130828 (EN)**

Application

**EP 08751792 A 20080522**

Priority

- JP 2008001280 W 20080522
- JP 2007136049 A 20070522

Abstract (en)

[origin: EP2153915A1] A sheet metal punching apparatus 1 includes an upper die holder 2 which is raised and lowered by a hydraulic ram and the like; a pressing plate 3 secured to the upper die holder 2; a pressing pad 5 suspended from the upper die holder 2 through a resilient member 4; a punch holder 7 constructed as a punch unit secured to the pressing pad 5 by means of a bolt 6 and the like; a lower die 9 on which thin sheet metal 8 to be subjected to punching is placed; and a die 10 embedded in the lower die 9.

IPC 8 full level

**B21D 28/34** (2006.01); **B21D 28/26** (2006.01)

CPC (source: EP KR US)

**B21D 28/26** (2013.01 - EP KR US); **B21D 28/34** (2013.01 - EP KR US)

Citation (search report)

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WO2013098154A1; EP2610019A1

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